

Title (en)
APPARATUS AND METHOD FOR PROCESSING SURFACES

Title (de)
VORRICHTUNG UND VERFAHREN ZUM BEARBEITEN VON OBERFLÄCHEN

Title (fr)
DISPOSITIF ET PROCÉDÉ POUR USINER DES SURFACES

Publication
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Application
EP 22700309 A 20220106

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Abstract (en)
[origin: WO2022148802A1] The invention relates to an apparatus (1) for processing surfaces, in particular floors, comprising a tool mechanism (4) having at least two tools (5a, 5b) movable relative to the tool mechanism (4), a tool motor (3) for driving the tools (5a, 5b), and a guide device (2) for guiding the apparatus (1) by a person. The apparatus (1) is designed such that, in a working position, it is only in direct contact with the surface by means of the tools (5a, 5b). The tool mechanism (4) comprises a circularly translational movement path for each of the tools (5a, 5b), wherein the movement path of the tools (5a, 5b) in each case runs in pairs in opposite directions. The apparatus (1) is also designed such that, when the apparatus (1) is in normal operation, the tools (5a, 5b) move with a cutting speed of at least 100 m/min along the circularly translational movement path. The movement path for each of the tools (5a, 5b) optionally comprises a travel of the tools (5a, 5b) of at least 10 mm.

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